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Alpha Assembly Solutions to Present at South East Asia Technical Conference on Electronics Assembly in Penang

Somerset, NJ – March 22, 2016 – Alpha Assembly Solutions, the world leader in the production of electronic soldering materials, will be presenting three technical papers “LED Die Attach Technologies – Trend and Considerations”, “High Reliability Interconnects for High Power LED Assembly” and “Methods for Minimizing Voiding in Surface Mount BGA and BTC Device Interconnects” at South East Asia Technical Conference which is hosted by SMTA from April 13-14, 2016 at Eastin Hotel in Penang, Malaysia.

The first paper titled “LED Die Attach Technologies – Trend and Considerations” will focus on the key role die-attach materials play in the performance and reliability of mid-power to super-high power LEDs. The presentation will provide an overview of different die attach technology platforms and discuss their attributes and fit with different chip structures operating at different power levels.

The second paper is titled “High Reliability Interconnects for High Power LED Assembly”. The topic addresses the need and impact for higher reliability interconnects for LED based outdoor and commercial lighting. The presentation will focus on the results of a recent assembly and reliability study of high power ceramic LEDs on aluminum metal core PCBs, and detail the impact of solder alloys on reliability.

The third paper titled “Methods for Minimizing Voiding in Surface Mount BGA and BTC Device Interconnects” will evaluate the causes of voids and focus on the methods of eliminating them. Six methods of reducing or eliminating voids in SMT applications will be discussed. Three of the techniques are process based adjustments and three involve the optimization of materials used in solder paste. These methods include:

- Reflow profile optimization
- Use of vacuum during reflow
- Managing the solder paste deposit volume through stencil design
- Solder paste chemistry selection
- Choice of solder powder particle size distribution
- Use of solvent-free joining materials

For more information on Alpha’s vast product offering and capabilities, visit AlphaAssembly.com
TECHNICAL PAPER PRESENTATION:

Wednesday, 13th April 2016 | 11:15-11:45  
Topic:  LED Die Attach Technologies – Trend and Considerations  
Speaker: Gyan Dutt, Technical Marketing Manager of LED – Alpha Assembly Solutions

Wednesday, 13th April 2016 | 17:15-17:45  
Topic:  High Reliability Interconnects for High Power LED Assembly  
Speaker: Amit Patel, Project Manager of LED – Alpha Assembly Solutions

Wednesday, 14th April 2016 | 15:00-15:30  
Topic:  Methods for Minimizing Voiding in Surface Mount BGA and BTC Device Interconnects  
Speaker: Mok Tuck Weng, Manager of Global Application Technology & Engineering – Alpha Assembly Solutions

Speakers’ Biography

Gyan Dutt works for Alpha as Technical Marketing Manager for LED Technologies. He is responsible for the planning, organization and implementation of the ALPHA® product portfolio for LED packaging, interconnect and assembly. He has more than 12 years of experience in technical marketing, product development and applications engineering in semiconductor packaging in the US and Asia-Pacific Regions.

Amit Patel is the Project Manager - Engineer, for the LED Technologies division at Alpha Assembly Solutions, South Plainfield, NJ. In his current role he is instrumental in planning, coordinating and executing market research, and applications research for the design and implementation of electronic assembly materials for all levels of LED manufacturing, from LED die attach to module/luminaire assembly. Amit holds a Bachelor's degree in Electrical Engineering from The New Jersey Institute of Technology. He is also an trained Six Sigma Black Belt. He co-wrote the iNEMI Solid State Illumination Technology Working Group for the 2015 roadmap cycle So far, He has published 3 papers in the areas covering Assembly Processes, and Thermal Management for the solid state lighting industry.

Mok Tuck Weng is a Manager – G.A.T.E. (Global Application Technology & Engineering) of Alpha Assembly Solutions, where he is responsible for handling customer's technical request with internal R&D and marketing team, participating in key technical areas of material development & process testing and providing backup to CTS concerning major developments or issues in Asia. Mr. Mok has joined Alpha since 2004 and he has over 27 years’ experience in electronic industry. He currently serves as Member of IPC, MTM and SMTA.

About Alpha Assembly Solutions

Alpha Assembly Solutions, a MacDermid Performance Solutions Business, is the global leader in the development, manufacturing and sales of innovative specialty materials used in a wide range of
industry segments, including electronics assembly, power electronics, die attach, LED lighting, photovoltaics, semiconductor packaging, automotive and others.

With a unique global presence in over 30 locations throughout the Asia Pacific, Americas and Europe regions, Alpha supplies a full line of ALPHA® electronics assembly material products, including Solder Paste, Exactalloy® Solder Preforms, Cored Solder Wire Solder, Wave Soldering Fluxes, Bar Solder Alloys, and Stencils. It offers die attach product technologies to the power electronics segment in its Argomax®, Atrox™ and Fortibond™ brands.

For the LED segment, Alpha offers its Lumet™ products covering applications from die attach to systems assembly in the LED manufacturing process. Alpha also offers product technologies for the Photovoltaic segment, including high performance liquid fluxes and solder alloys for producing standard ribbon and bus bar, as well as, solder pastes, cored wire, conductive adhesives and preforms for use in PV module assembly. Also, Alpha’s Advanced Materials unit is the leader in electronic polymers and solder materials for semiconductor packaging applications.

Since its founding in 1872, Alpha has been committed to developing and manufacturing the highest quality specialty materials. For more information, visit AlphaAssembly.com.

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